



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-08-02
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB22N60DM6	TLD2*PQ64B62	A	3068	2018-08-02
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.14	Die - Leadframe	99
Lead	7.68	Soft solder	5562

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	7.68	Soft solder	5562
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	7.675	Soft solder	954958

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLD2*PQ64862					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	6.375	mg	supplier	die	Silicon (Si)	7440-21-3		6.175	mg	968627	4475
				supplier	metallization	Aluminium (Al)	7429-90-5		0.081	mg	12706	59
				supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	5491	25
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	627	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.059	mg	9255	43
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.021	mg	3294	15
Leadframe	M-004 Copper and its alloys	778.632	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.536	mg	998592	563432
				supplier	alloy	Iron (Fe)	7439-89-6		0.779	mg	1000	562
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.234	mg	301	170
				supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	99	56
				supplier	metallization	Phosphorus (P)	7723-14-0		0.006	mg	8	4
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	7.675	mg	954958	5562
Soft solder	Solder	8.037	mg	supplier	solder	Silver (Ag)	7440-22-4		0.201	mg	25010	146
				supplier	solder	Tin (Sn)	7440-31-5		0.161	mg	20032	117
				supplier	wire	Aluminium (Al)	7429-90-5		0.771	mg	996124	559
Bonding wires	M-003 Aluminum and its alloys	0.774	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.003	mg	3876	2
				supplier	wire	Silica, vitreous	60676-86-0		510.730	mg	874998	370094
Encapsulation	M-011 Other inorganic materials	583.693	mg	supplier	mold compound	Tetramethyl-biphenyl-diy-bis oxymethylene-bi	EC 413-900-7		23.348	mg	40000	16919
				supplier	mold compound	Epoxy Resin	25068-38-6		17.511	mg	30000	12689
				supplier	mold compound	phenol resin	29690-82-2		29.185	mg	50001	21149
				supplier	mold compound	Carbon black	1333-86-4		2.919	mg	5001	2115
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804